

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

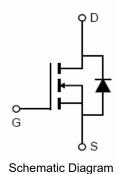
General Features

- V_{DS} =85V, I_D =140A $R_{DS(ON)}$ =3.5m Ω , typical (TO-220)@ V_{GS} =10V $R_{DS(ON)}$ =3.3m Ω , typical (TO-263)@ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating





TO-263



Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|-----------|----------------|-----------|------------|----------|
| VST08N035-TC | VST08N035 | TO-220C | - | - | - |
| VST08N035-T3 | VST08N035 | TO-263 | - | - | - |

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

| Parameter | Symbol | Limit | Unit | |
|--|-----------------------|---|------|--|
| Drain-Source Voltage | V _{DS} | 85 | V | |
| Gate-Source Voltage | V _G s | ±20 | V | |
| Drain Current-Continuous | I _D | 140 | А | |
| Drain Current-Continuous(T _C =100°C) | I _D (100℃) | 99 | А | |
| Pulsed Drain Current | I _{DM} | 560 | Α | |
| Maximum Power Dissipation | P _D | 200 | W | |
| Derating factor | | 1.33 | W/℃ | |
| Single pulse avalanche energy (Note 5) | E _{AS} | 1050 | mJ | |
| Operating Junction and Storage Temperature Range | T_{J}, T_{STG} | T _J ,T _{STG} -55 To 175 | | |



Thermal Characteristic

Electrical Characteristics (T_c=25°Cunless otherwise noted)

| Parameter | Symbol | Condition | | Min | Тур | Max | Unit |
|------------------------------------|---------------------|---|-----------------------|-----|------|------|------|
| Off Characteristics | | | | • | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | | 85 | | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =85V,V _{GS} =0V | | - | - | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V,V _{DS} =0V | | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | · I | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | V _{DS} =V _{GS} ,I _D =250μA | | 2.0 | 3.0 | 4.0 | V |
| Dunin Course On State Besistance | Б | V _{GS} =10V, I _D =70A | TO-220 | - | 3.5 | 4.0 | mΩ |
| Drain-Source On-State Resistance | R _{DS(ON)} | | TO-263 | | 3.3 | 4.0 | mΩ |
| Forward Transconductance | g FS | $V_{DS}=5V,I_{D}=$ | V,I _D =70A | | 90 | - | S |
| Dynamic Characteristics (Note4) | | | | • | | | |
| Input Capacitance | C_{lss} | - V _{DS} =40V,V _{GS} =0V, - F=1.0MHz | | - | 4950 | - | PF |
| Output Capacitance | Coss | | | - | 850 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | | | - | 40 | - | PF |
| Switching Characteristics (Note 4) | · | | | • | | | |
| Turn-on Delay Time | t _{d(on)} | V_{DD} =40V, I_{D} =70A V_{GS} =10V, R_{G} =1.6 Ω | | - | 18 | - | nS |
| Turn-on Rise Time | t _r | | | - | 11 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | | - | 38 | - | nS |
| Turn-Off Fall Time | t _f | | | - | 9 | - | nS |
| Total Gate Charge | Qg | - V _{DS} =40V,I _D =70A, - V _{GS} =10V | | - | 88 | - | nC |
| Gate-Source Charge | Q_{gs} | | | - | 22 | | nC |
| Gate-Drain Charge | Q_{gd} | | | - | 25 | | nC |
| Drain-Source Diode Characteristics | | | | • | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | V _{GS} =0V,I _S =70A | | - | | 1.2 | V |
| Diode Forward Current (Note 2) | Is | | | - | - | 140 | Α |
| Reverse Recovery Time | t _{rr} | T _J = 25°C, I _F = 70A | | - | 72 | - | nS |
| Reverse Recovery Charge | Qrr | di/dt = 100A/µs ^(Note3) | | - | 102 | - | nC |

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V_DD=40V,V_G=10V,L=0.5mH,Rg=25 Ω





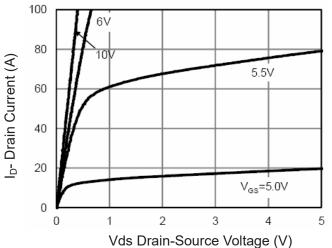


Figure 1 Output Characteristics

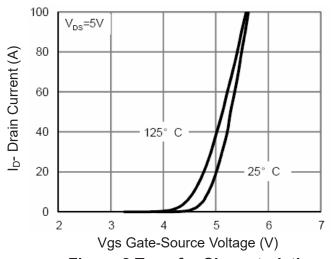


Figure 2 Transfer Characteristics

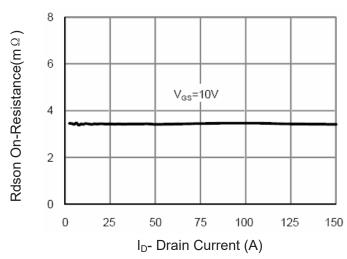


Figure 3 Rdson- Drain Current

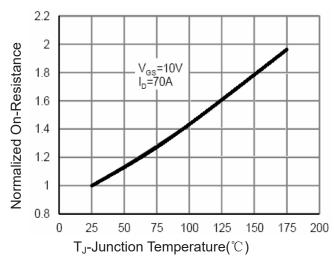


Figure 4 Rdson-Junction Temperature

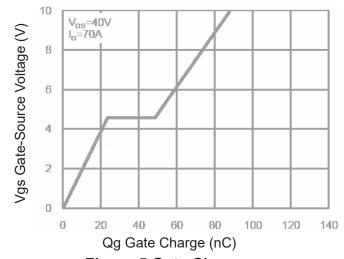


Figure 5 Gate Charge

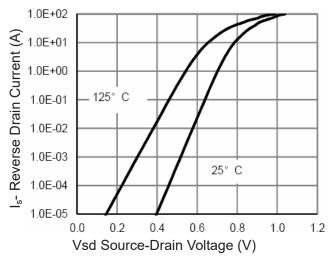


Figure 6 Source- Drain Diode Forward



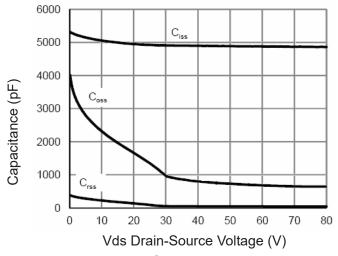


Figure 7 Capacitance vs Vds

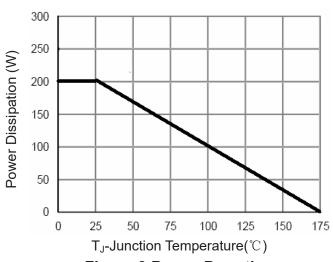


Figure 9 Power De-rating

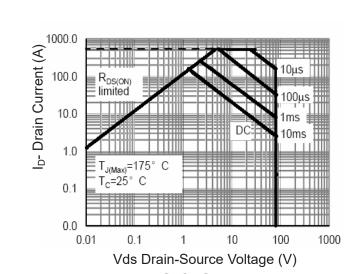


Figure 8 Safe Operation Area

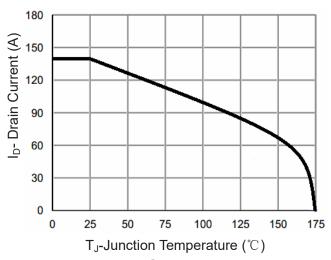


Figure 10 Current De-rating

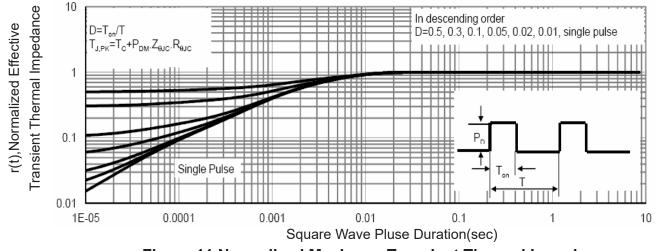


Figure 11 Normalized Maximum Transient Thermal Impedance